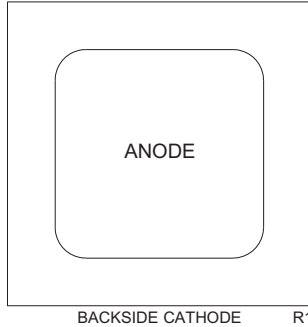


CPD24-CMR1F-06M

Fast Rectifier Die

1.0 Amp, 600 Volt

The CPD24-CMR1F-06M is a silicon 1.0 Amp, 600 Volt fast recovery rectifier ideal for all types of commercial, industrial, entertainment, and computer applications.



MECHANICAL SPECIFICATIONS:

Die Size	50.5 x 50.5 MILS
Die Thickness	11 MILS
Anode Bonding Pad Size	33.8 x 33.8 MILS
Top Side Metalization	Ni/Au – 4,500Å/1,350Å
Back Side Metalization	Ni/Au – 4,500Å/1,350Å
Scribe Alley Width	2.0 MILS
Wafer Diameter	4 INCHES
Gross Die Per Wafer	4,250

MAXIMUM RATINGS: (T_A=25°C)

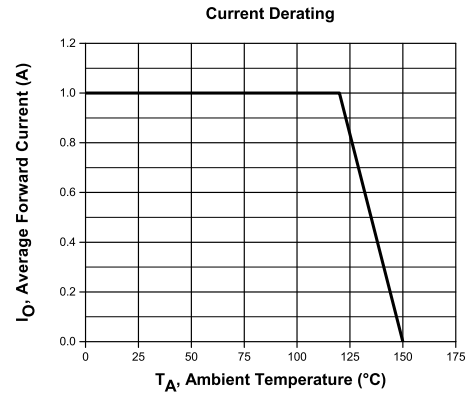
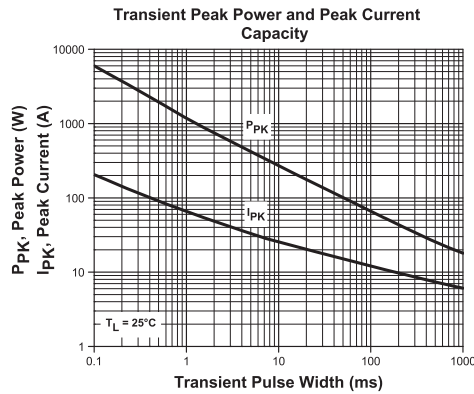
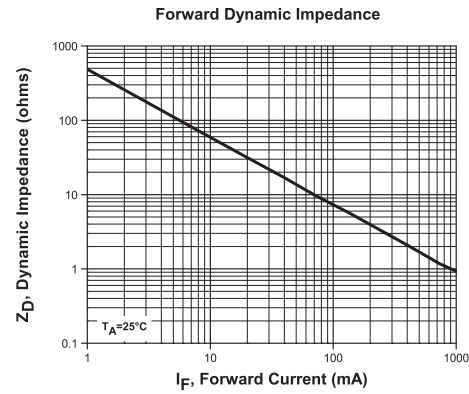
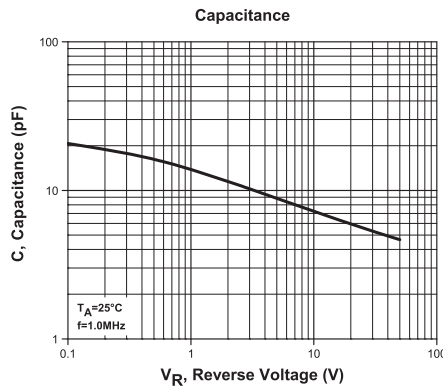
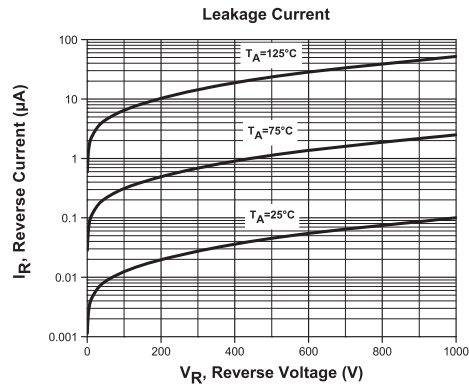
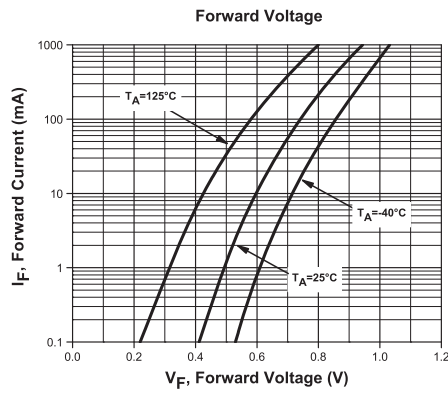
	SYMBOL		UNITS
Peak Repetitive Reverse Voltage	V _{RRM}	600	V
DC Blocking Voltage	V _R	600	V
RMS Reverse Voltage	V _{R(RMS)}	420	V
Average Forward Current (T _A =120°C)	I _O	1.0	A
Peak Forward Surge Current, tp=8.3ms	I _{FSM}	30	A
Operating and Storage Junction Temperature	T _J , T _{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS: (T_A=25°C unless otherwise)

SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I _R	V _R =600V		5.0	μA
V _F	I _F =1.0A		1.3	V
C _J	V _R =0, f=1.0MHz		35	pF
t _{rr}	I _F =0.5A, I _R =1.0A, I _{rr} =0.25A		250	ns

CPD24-CMR1F-06M

Typical Electrical Characteristics



BARE DIE PACKING OPTIONS



BARE DIE IN TRAY (WAFFLE) PACK

CT: Singulated die in tray (waffle) pack.
(example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).
(example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked.
(example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,
100% tested with reject die inked.
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications:
www.centrasemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

REQUESTING PRODUCT PLATING

1. If requesting Tin/Lead plated devices, add the suffix " TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.
145 Adams Avenue
Hauppauge, NY 11788 USA
Main Tel: (631) 435-1110
Main Fax: (631) 435-1824
Support Team Fax: (631) 435-3388
www.centrasemi.com

Worldwide Field Representatives:
www.centrasemi.com/wwreps

Worldwide Distributors:
www.centrasemi.com/wwdistributors

For the latest version of Central Semiconductor's **LIMITATIONS AND DAMAGES DISCLAIMER**, which is part of Central's Standard Terms and Conditions of sale, visit: www.centrasemi.com/terms